

Agenda

“Will the advent of 3D monolithic integration eliminate the need for higher lithographic resolution?”

- 1:00-1:10 Welcome and Introductions. Paolo Gargini
- 1:10-1:30. Overview. Paolo Gargini
- 1:30-1:50. Lithography status and
• IMEC view of 3D-enabled scaling IMEC. Greg McIntyre
- 1:50-2:20. 3D impact on depositions and etch. Uday Mitra
- 2:20-2:40. Nano-Devices for 3D Logic. Jeff Bokor
- 2:40-3:00. Components of 3D architecture. Erik DeBenedictis
- 3:00-3:30. Coffee break
- 3:30-5:30. Panel discussion. All

Panel Discussion

“Will the advent of 3D monolithic integration eliminate the need for higher lithographic resolution?”

Moderator: Paolo Gargini, Chairman IRDS* and IEUVI**

Panelists:

- Greg McIntyre: Director of Advanced Patterning, IMEC
- Uday Mitra: VP and CTO Patterning and Etch, AMAT
- Jeff Bokor: Associate Dean for Research in the UC Berkeley College of Engineering
- Erik DeBenedictis: Supercomputers and RCI***, Sandia Nat Lab

* International Roadmap for Devices and Systems

** International EUV Initiative

***Rebooting Computing Initiative